



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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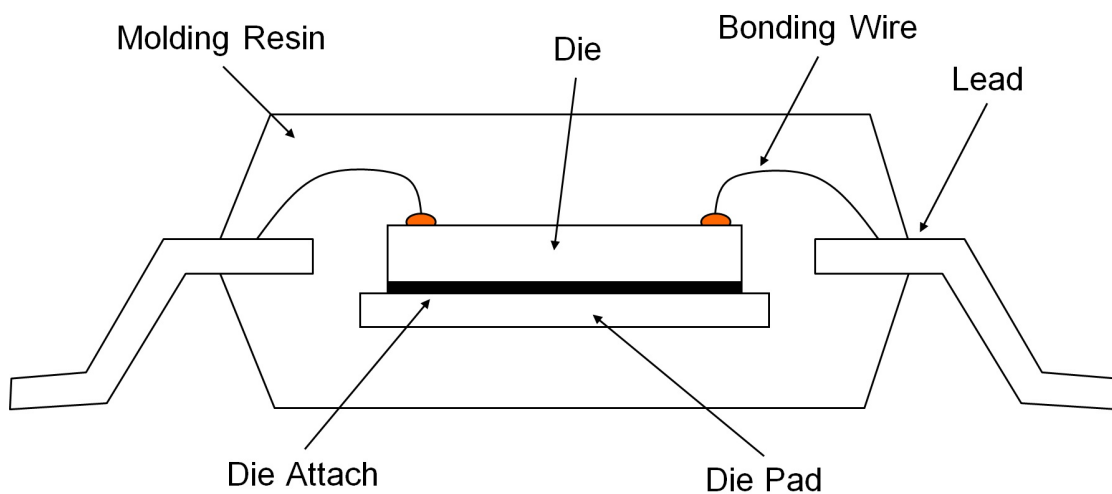
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



1. Package Information

Package Name	VQFP64
Type	QFP
Pin Count	64
Outline Dimension	EX252-5001-1
Drawing No.	
Package Weight [g]	0.35
Lead Finish	Pure Tin
MSL Level	Level3

2. Package Structure



3. Packing Specification

3.1 Packing form, Quantity, PIN1 Orientation

Packing Form		Tape&Reel
Packing Quantity	[pcs]	1,000
PIN 1 Orientation		E2

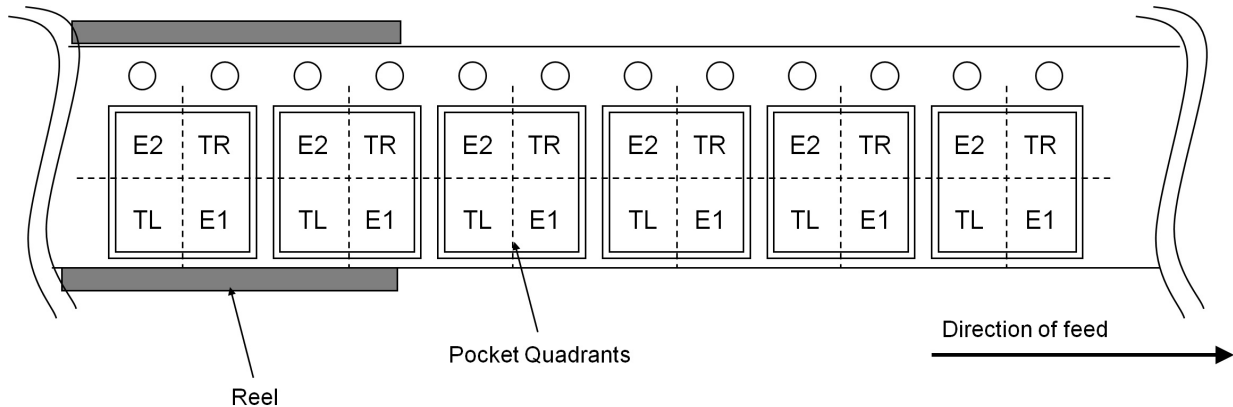


Fig.1 Quadrant Assignments for PIN 1 Orientation in Tape

- E2 : PIN1 is placed to the top left corner.
- TR : PIN1 is placed to the top right corner.
- TL : PIN1 is placed to the lower left.
- E1 : PIN1 is placed to the lower right.

3.2 Use material

Item	Material
Embossed carrier tape	PS
Cover tape	PET+PE
Reel	PS
Desiccant	Silicagel
Envelope	Aluminum-laminated
Air cap	PE
Unit box	Cardboard
Shipping box	Cardboard

3.3 Leader specification

No component pockets are 640 mm or more.

3.4 Trailer specification

No component pockets are 160 mm or more. Tape is free from reel.

3.5 Peelback strength

Cover tape peelback strength is 0.2 N to 0.7 N.

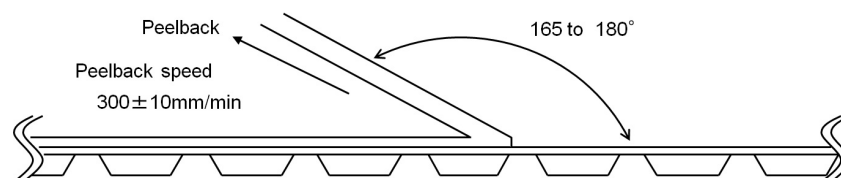


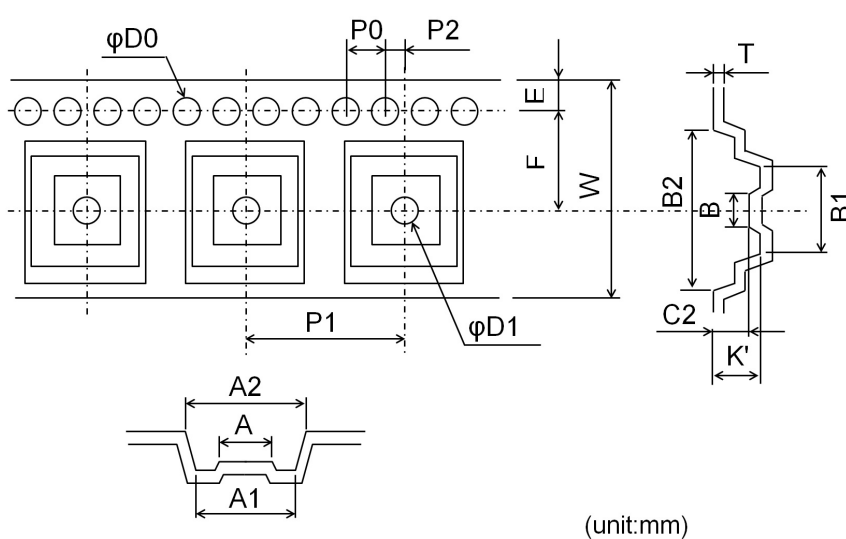
Fig. 2 Test method

3.6 Missing lcs

- (1) No consecutive dropouts.
- (2) A maximum 0.1 % of specified number of products in each packing may be missing.

3.7 Tape and Reel Specification

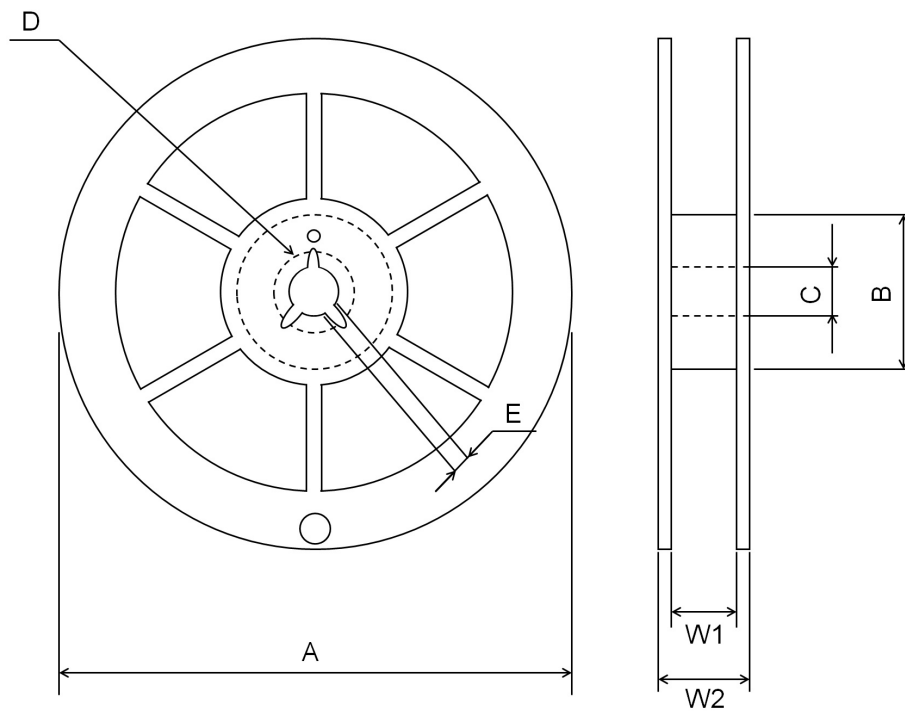
3.7.1 Tape Dimension



(unit:mm)

	Tape Dimension	Tape Tolerance
A	9.00	-
A1	12.5	± 0.1
A2	12.8	± 0.1
B	9.00	-
B1	12.5	± 0.1
B2	16.8	+0.15/-0.05
C2	1.70	± 0.1
D0	$\phi 1.5$	+0.1/-0
D1	$\phi 2.0$	+0.1/-0
E	1.75	± 0.1
F	11.5	± 0.1
K'	2.20	± 0.1
P0	4.00	± 0.1
P1	16.0	± 0.1
P2	2.00	± 0.1
T	0.30	± 0.05
W	24.0	± 0.3

3.7.2 Reel Dimension

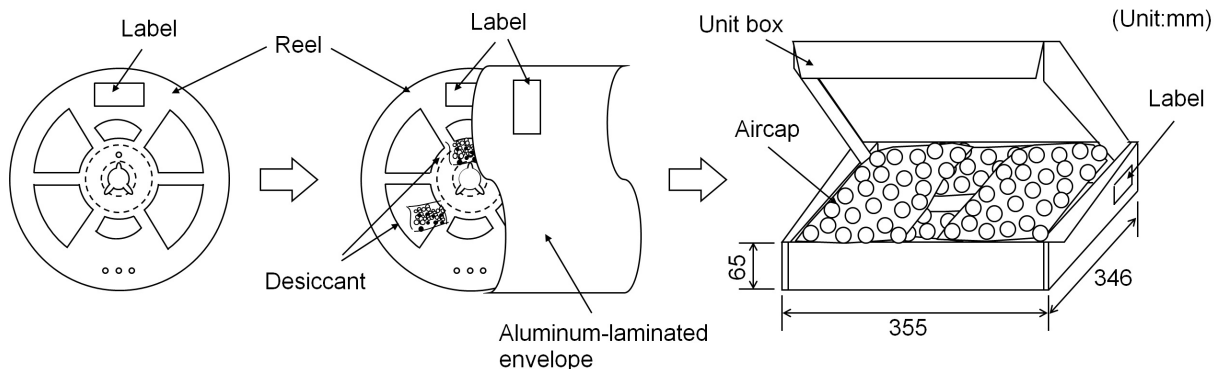


(unit:mm)

	Reel Dimension	Reel Tolerance
A	330	±2.0
B	100	±1.0
C	13	±0.2
D	21	±0.8
E	2	±0.5
W1	25.5	±1.0
W2	29.5	±1.0

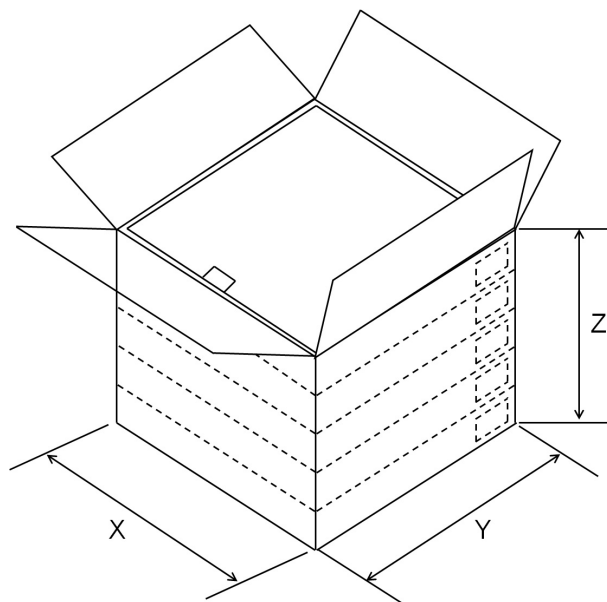
3.8 Packing Method

1 reel(s) or less per unit box



3.9 Packing Style

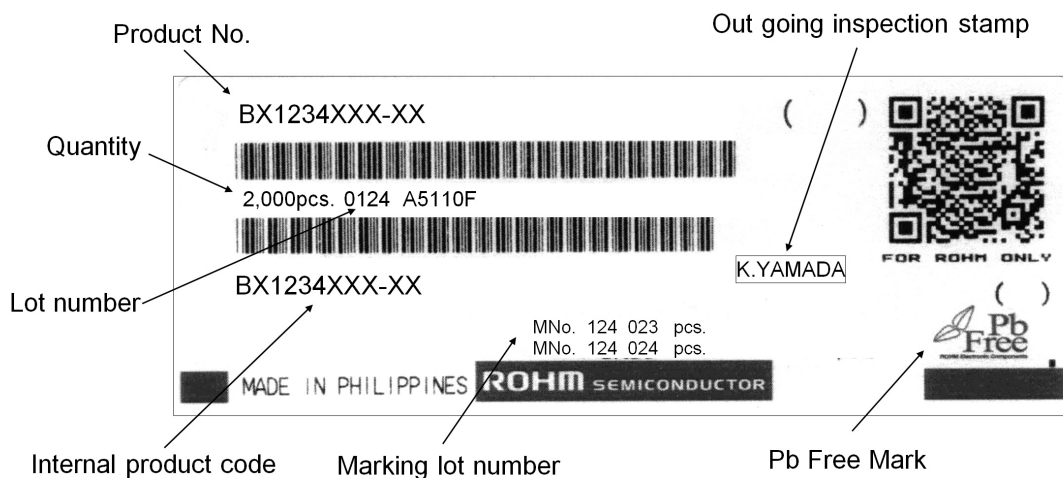
5 unit boxes or less per shipping box



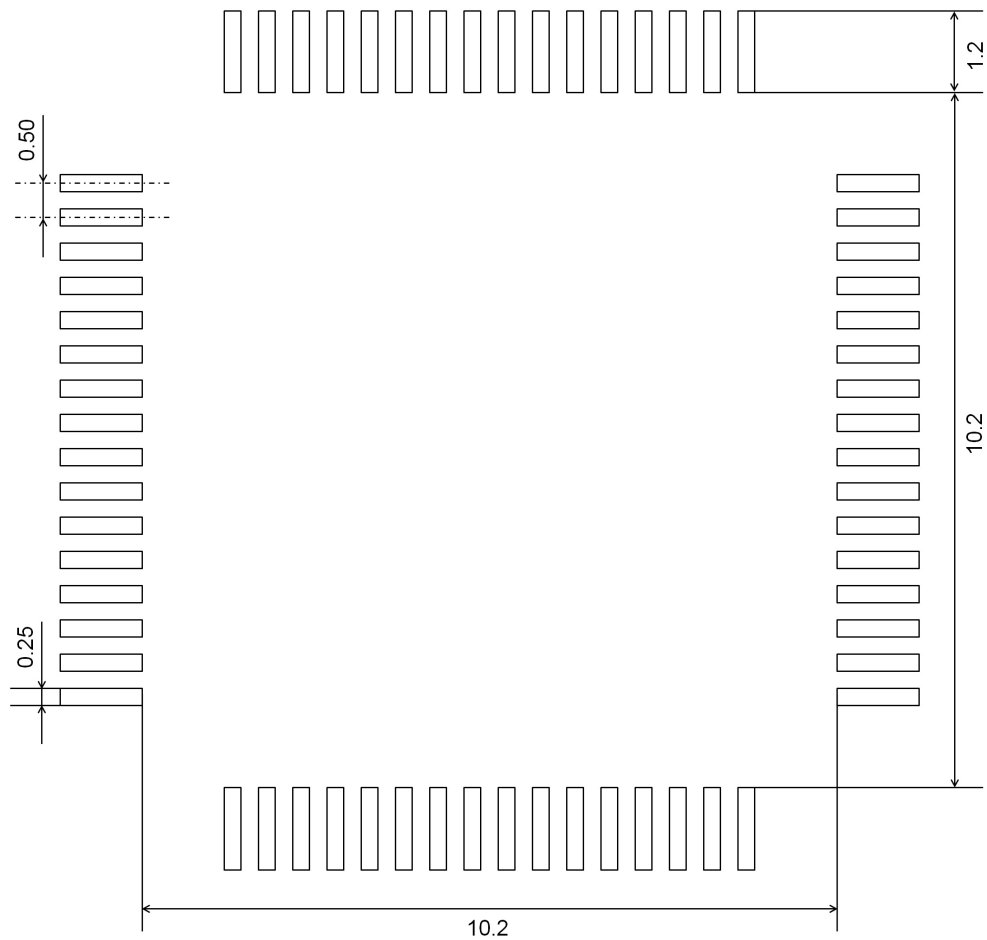
(unit:mm)

Shipping Box Dimension	
X	372
Y	368
Z	355

3.10 Label Specification



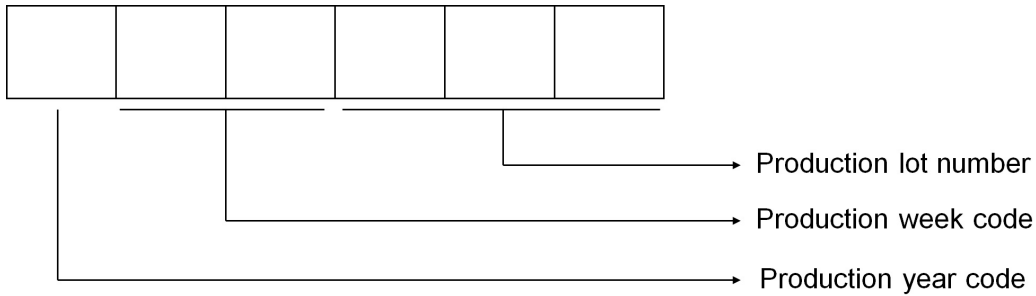
4. Footprint dimensions



(unit:mm)

In actual design, please optimize in accordance with the situation of your board design and soldering condition.

5. Marking Specification



6. Storage conditions

6.1 Storage environment

Recommended storage conditions

	Min.	Max.	Unit
Temperature	5	30	°C
Humidity	40	70	% RH

6.2 Storage period

	Min.	Max.	Unit
Storage period	-	1	year

6.3 Specified storage period until soldering

	Min.	Max.	Unit
Acceptable time	-	168	hour

The above value is a time from opening the moisture-proof packaging until the soldering.

Cases where it is necessary to perform the drying process is the following.

Case 1 : in excess of the above-mentioned "Acceptable time"

Case 2 : it has passed more than a year not open

Recommended the dry process conditions

	Temperature [°C]	Time [hour]
Reel (Note1)	60	48
Other Heat-proof container	125	24

(Note1) When carrying out the dry process in a "Reel" state, the peelback strength will change.

Please refer to the following values:

	Min.	Max.	Unit
Peelback strength	0.2	0.9	N

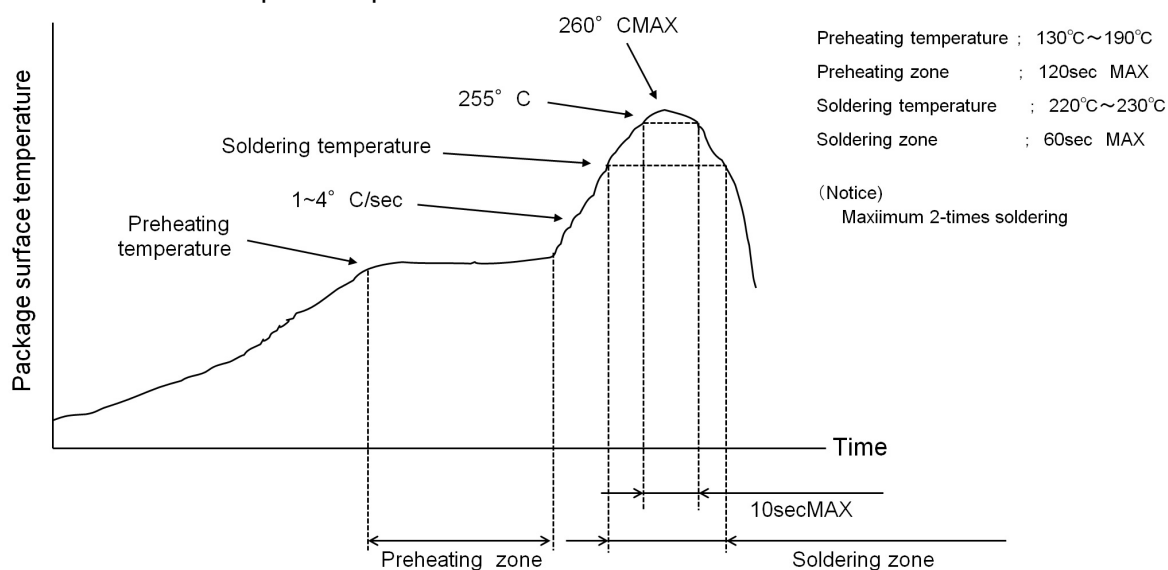
The drying process is the impact on the solderability because the oxidation of the terminal portion will occur. Therefore, specify the maximum times of the dry processing as follows:

Recommended execution count of the dry process

	Min.	Max.	Unit
Execution count	-	2	times

7. Soldering conditions

7.1 Recommended temperature profile for reflow



7.2 Recommended condition for wave soldering

Preheating temperature	:	120 °C to 150 °C
Preheating time	:	60 sec MAX
Soldering temperature	:	260 °C ± 3 °C
Soldering time	:	12 sec MAX

Notes for wave soldering

- (1) Soldering time is provided for total soldering time in case of dual wave soldering.
- (2) Do not use other soldering methods with wave soldering.
- (3) Recommend to clean the board to eliminate flux, solder waste, and other impurities for reliability, after soldering.
- (4) Optimize soldering condition to prevent solder bridging.

7.3 Recommended condition for solder iron

Solder iron temperature	:	380 °C or less
Mounting time	:	4 sec or less

Notes

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